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| APPLICATION NO. | FILING DATE | FIRST NAMED INVENTOR | ATTORNEY DOCKET NO. | CONFIRMATION NO. |
|-----------------|-------------|----------------------|---------------------|------------------|
| 10/026,760 | 12/27/2001 | Byoung Ho Lim | 049128-5053 | 9786 |

9629 7590 02/20/2004

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| EXAMINER |
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LANDAU, MATTHEW C

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| ART UNIT | PAPER NUMBER |
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2815

DATE MAILED: 02/20/2004

Please find below and/or attached an Office communication concerning this application or proceeding.

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|------------------------|-------------------------------|--------------------------------|--|
| Advisory Action | Application No. 10/026,760 | Applicant(s) LIM, BYOUNG HO | |
| | Examiner Matthew Landau | Art Unit 2815 | |

--Th MAILING DATE of this communication appears on the cover sheet with the correspondenc address --

THE REPLY FILED 30 January 2004 FAILS TO PLACE THIS APPLICATION IN CONDITION FOR ALLOWANCE. Therefore, further action by the applicant is required to avoid abandonment of this application. A proper reply to a final rejection under 37 CFR 1.113 may only be either: (1) a timely filed amendment which places the application in condition for allowance; (2) a timely filed Notice of Appeal (with appeal fee); or (3) a timely filed Request for Continued Examination (RCE) in compliance with 37 CFR 1.114.

PERIOD FOR REPLY [check either a) or b)]

- a) ☒ The period for reply expires 3 months from the mailing date of the final rejection.
- b) ☐ The period for reply expires on: (1) the mailing date of this Advisory Action, or (2) the date set forth in the final rejection, whichever is later. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the mailing date of the final rejection. ONLY CHECK THIS BOX WHEN THE FIRST REPLY WAS FILED WITHIN TWO MONTHS OF THE FINAL REJECTION. See MPEP 706.07(f).

Extensions of time may be obtained under 37 CFR 1.136(a). The date on which the petition under 37 CFR 1.136(a) and the appropriate extension fee have been filed is the date for purposes of determining the period of extension and the corresponding amount of the fee. The appropriate extension fee under 37 CFR 1.17(a) is calculated from: (1) the expiration date of the shortened statutory period for reply originally set in the final Office action; or (2) as set forth in (b) above, if checked. Any reply received by the Office later than three months after the mailing date of the final rejection, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

1. ☐ A Notice of Appeal was filed on _____. Appellant's Brief must be filed within the period set forth in 37 CFR 1.192(a), or any extension thereof (37 CFR 1.191(d)), to avoid dismissal of the appeal.
2. ☒ The proposed amendment(s) will not be entered because:
- (a) ☒ they raise new issues that would require further consideration and/or search (see NOTE below);
 - (b) ☐ they raise the issue of new matter (see Note below);
 - (c) ☒ they are not deemed to place the application in better form for appeal by materially reducing or simplifying the issues for appeal; and/or
 - (d) ☐ they present additional claims without canceling a corresponding number of finally rejected claims.

NOTE: See Continuation Sheet.

3. ☐ Applicant's reply has overcome the following rejection(s): _____.
4. ☐ Newly proposed or amended claim(s) _____ would be allowable if submitted in a separate, timely filed amendment canceling the non-allowable claim(s).
5. ☐ The a) ☐ affidavit, b) ☐ exhibit, or c) ☐ request for reconsideration has been considered but does NOT place the application in condition for allowance because: _____.
6. ☐ The affidavit or exhibit will NOT be considered because it is not directed SOLELY to issues which were newly raised by the Examiner in the final rejection.
7. ☒ For purposes of Appeal, the proposed amendment(s) a) ☒ will not be entered or b) ☐ will be entered and an explanation of how the new or amended claims would be rejected is provided below or appended.

The status of the claim(s) is (or will be) as follows:

Claim(s) allowed: _____.

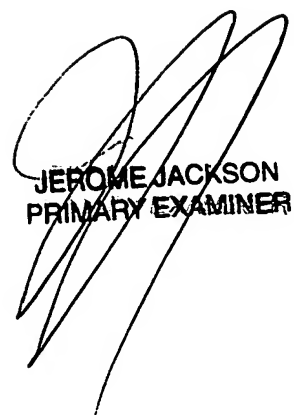
Claim(s) objected to: _____.

Claim(s) rejected: 1-21.

Claim(s) withdrawn from consideration: _____.

8. ☐ The drawing correction filed on _____ is a) ☐ approved or b) ☐ disapproved by the Examiner.
9. ☐ Note the attached Information Disclosure Statement(s) (PTO-1449) Paper No(s). _____.
10. ☐ Other: _____

Continuation of 2. NOTE: The proposed amendment, including the limitations "to remove an impurity thereon" and "simultaneously", raises new issues that would require further consideration and/or search.



JEROME JACKSON
PRIMARY EXAMINER

IN THE CLAIMS:

Claim 1 (Currently Amended): A method of fabricating a liquid crystal display panel, comprising the steps of:

preparing an upper substrate and a lower substrate;

bonding the upper substrate to the lower substrate;

cleaning exposed surfaces of the bonded upper and lower substrates to remove an impurity thereon; and

simultaneously eliminating the exposed surfaces of the bonded upper and lower substrates.

Claim 2 (Original): The method according to claim 1, wherein the step of cleaning exposed surfaces includes dry-etching.

Claim 3 (Original): The method according to claim 1, wherein the step of eliminating the exposed surfaces includes wet-etching.

Claim 4 (Original): The method according to claim 1, further including the steps of:

- forming a thin film transistor on the lower substrate;
- forming a protective layer on the lower substrate; and
- forming a pixel electrode on the protective layer to electrically contact the thin film transistor.

Claim 5 (Previously Presented): The method according to claim 4, wherein the pixel electrode is formed of a transparent conductive material including one of indium-tin-oxide (ITO), indium-zinc-oxide (IZO), and indium-tin-zinc-oxide (ITZO).

Claim 6 (Currently Amended): The method according to claim 4, wherein the protective layer is formed of an organic insulating material including one of an acrylic organic compound, ~~TEFLON~~[®] fluorinated polymer, benzocyclobutene (BCB), ~~Cytop~~[®], and perfluorocyclobutane (PFCB).

Claim 7 (Original): The method according to claim 4, wherein the step of forming the thin film transistor includes:

- forming a gate electrode on the lower substrate;
- forming a gate insulating film on the lower substrate to cover the gate electrode;

forming an active layer on the gate insulating film; and
forming a source electrode and a drain electrode on the active layer.

Claim 8 (Original): The method according to claim 7, wherein the source electrode and drain electrode contact the gate insulating film.

Claim 9 (Previously Presented): The method according to claim 7, wherein the pixel electrode contacts flat and inclined surfaces of the drain electrode via a contact hole to expose the drain electrode.

Claim 10 (Currently Amended): A method of fabricating a liquid crystal display panel, comprising the steps of:

bonding an upper substrate to a lower substrate;
cleaning exposed surfaces of the bonded upper and lower substrates to remove an impurity thereon; and
simultaneously removing the exposed surfaces of the bonded upper and lower substrates.

Claim 11 (Original): The method according to claim 10, wherein the step of cleaning exposed surfaces includes dry-etching.

Claim 12 (Original): The method according to claim 10, wherein the step of removing the exposed surfaces includes wet-etching.

Claim 13 (Original): The method according to claim 10, wherein the step of removing the exposed surfaces uniformly reduces a thickness of the liquid crystal display panel.

Claim 14 (Currently Amended): A method of fabricating a liquid crystal display panel, comprising the steps of:

- forming a gate electrode on a lower substrate;

- forming a gate insulating film on the lower substrate to cover the gate electrode;

- forming an active layer on the gate insulating film; and

- forming a source electrode and a drain electrode on the active layer;

- bonding an upper substrate to the lower substrate;

- cleaning exposed surfaces of the bonded upper and lower substrates to remove an impurity thereon; and

- simultaneously removing the exposed surfaces of the bonded upper and lower substrates.

Claim 15 (Original): The method according to claim 14, wherein the step of cleaning exposed surfaces includes dry-etching.

Claim 16 (original): The method according to claim 14, wherein the step of removing the exposed surfaces includes wet-etching.

Claim 17 (Original): The method according to claim 14, further including the steps of
forming a protective layer on the lower substrate; and
forming a pixel electrode on the protective layer to electrically contact the drain electrode.

Claim 18 (Previously Presented): The method according to claim 17, wherein the pixel electrode is formed of a transparent conductive material including one of indium-tin-oxide (ITO), indium-zinc-oxide (IZO), and indium-tin-zinc-oxide (ITZO).

Claim 19 (Currently Amended): The method according to claim 17, wherein the protective layer is formed of an organic insulating material including one of an acrylic organic compound, ~~TEFLON~~[®] fluorinated polymer, benzocyclobutene (BCB), ~~Cytep~~[®], and perfluorocyclobutane (PFCB).

Claim 20 (Original): The method according to claim 14, wherein the step of removing the exposed surfaces uniformly reduces a thickness of the liquid crystal display panel.

Claim 21 (Previously Presented): The method according to claim 1, wherein the step of eliminating the exposed surfaces of the bonded upper and lower substrates uniformly reduces a thickness of the liquid crystal panel.